



Final Product/Process Change Notification

Document #:FPCN25729XC1

Issue Date:09 Oct 2024

Title of Change:	Update to FPCN25729XC - Change to Dual Source Wafer Fab Strategy at LA Semiconductor and onsemi Bucheon, Korea for ESD and Surge Protection Products and adding datasheet update.
Proposed First Ship date:	16 Jan 2025 or earlier if approved by customer
Contact Information:	Contact your local onsemi Sales Office or NoorArdila.Shaharuddin@onsemi.com
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local onsemi Sales Office or Nicky.Siu@onsemi.com
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com
Marking of Parts/ Traceability of Change:	Changed material can be identified by lot code
Change Category:	Wafer Fab Change
Change Sub-Category(s):	Datasheet/Product Doc change, Manufacturing Site Addition

Sites Affected:

onsemi Sites

onsemi Bucheon, Korea

External Foundry/Subcon Sites

None

Description and Purpose:

This update notification is to advise customers of the dual source wafer fab strategy for the devices listed in the Affected Parts List.

Upon implementation of this FPCN, parts can be sourced from either LA Semiconductor or onsemi Bucheon, Korea.

	From	To
Manufacturing location for Wafer Fab	LA Semiconductor, Idaho, United States	LA Semiconductor, Idaho, United States onsemi Bucheon, Korea

The datasheet limits for part numbers **ESD9M5.0ST5G**, and **ESD9P5.0ST5G** are also updated as a standardization practice.

Products not listed in the table below are not affected by the limit standardization exercise.

OPN	Vbr min	
	Before	After
ESD9M5.0ST5G	5.8	5.4
ESD9P5.0ST5G	5.8	5.4

There is no product marking changes as a result of this change.



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Reliability Data Summary:

QV DEVICE NAME: ESD9M5.0ST5G

RMS: 97093

PACKAGE: SOD923

Test	Specification	Condition	Interval	Results
High Temperature Reverse Bias	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs	0/231
High Temperature Storage Life	JESD22-A103	Ta=150°C	1008 hrs	0/231
Preconditioning	J-STD-020 JESD-A113	MSL 1 @260°C		
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/231
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/231
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231

Electrical Characteristics Summary:

Limits have been changed per described in the details section for standardization purposes for part numbers **ESD9M5.0ST5G**, and **ESD9P5.0ST5G** only.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
ESD9R3.3ST5G	ESD9M5.0ST5G
ESD9P5.0ST5G	ESD9M5.0ST5G
ESD9M5.0ST5G	ESD9M5.0ST5G
ESD9L5.0ST5G	ESD9M5.0ST5G
ESD9L3.3ST5G	ESD9M5.0ST5G